Specification for Approval

Customer:_____

Model Name:_____

Supplier Approval			Customer approval
R&D Designed	R&D Approved	QC Approved	
Peter	*Peng Jun*		

Revision Record

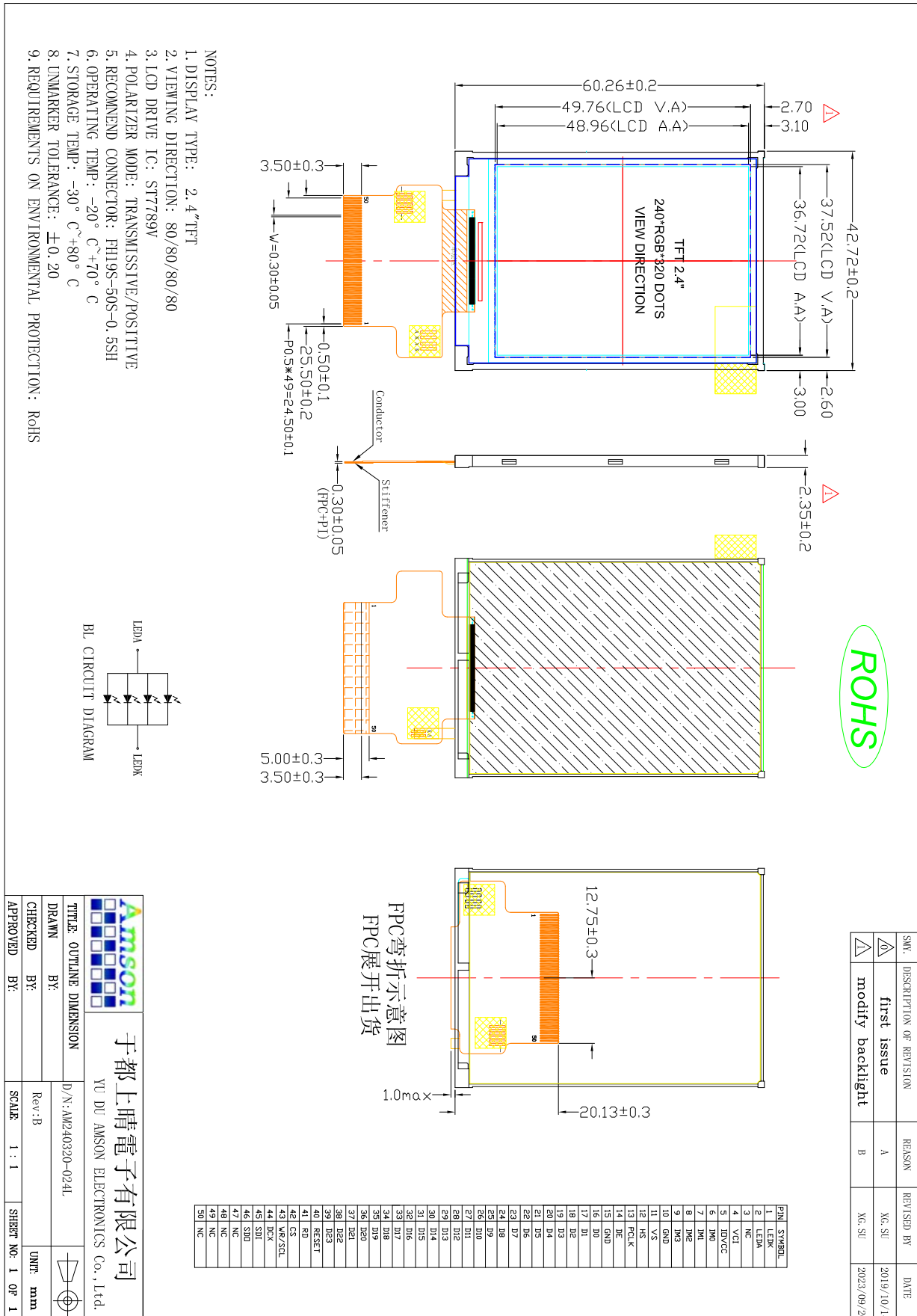| REV NO.	REV DATE	CONTENTS	Note
A	2020-03-12	NEW ISSUE	
B	2022-09-01	MODIFY 11.4 STANDARD OF VIDUAL INSPECTION	
C	2023-09-20	MODIFY BACKLIGHT	

Table of Contents

1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution

2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	2.4"TFT	--
Dot arrangement	240(RGB)×320	dots
Color filter array	RGB vertical stripe	--
Display mode	Transmission / Normally Black	-
Gray Scale Inversion Direction	80/80/80/80	--
Eyes Viewing Direction	ALL	--
Driver IC	ST7789V	--
Module size	42.72 (W)×60.26(H)×2.35(T)	mm
Active area	36.72(W)×48.96(H)	mm
Dot pitch	0.153(W)×0.153(H)	mm
Interface	i80-system 8/16/18-bit MCU interface 3SPI/4SPI/ 16/18-bit RGB interface	--
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	4 White LED	--

3. External Dimensions

NOTES:
1.DISPLAY TYPE: 2.4"TFT
2.VIEWING DIRECTION: 80/80/80/80
3.LCD DRIVE IC: ST7789V
4.POLARIZER MODE: TRANSMISSIVE/POSITIVE
5.RECOMMEND CONNECTOR: FH19S-50S-0.5SH
6.OPERATING TEMP: -20°C~+70°C
7.STORAGE TEMP: -30°C~+80°C
8.UNMARKER TOLERANCE: ±0.20
9.REQUIREMENTS ON ENVIRONMENTAL PROTECTION: RoHS

60.26±0.2
49.76(LCD V.A)
48.96(LCD A.A)
2.70
3.10
37.52(LCD V.A)
36.72(LCD A.A)
42.72±0.2
2.60
3.00

3.50±0.3
W=0.30±0.05
0.50±0.1
25.50±0.2
P0.5*49=24.50±0.1

TFT 2.4"
240*RGB*320 DOTS
VIEW DIRECTION

Conductor
Stiffener
0.30±0.05
(FPC+PI)
2.35±0.2

LEDA
LEDK
BL. CIRCUIT DIAGRAM

5.00±0.3
3.50±0.3

ROHS

FPC弯折示意图
FPC展开出货

12.75±0.3
1.0max
20.13±0.3

PIN	SYMBOL
1	LEDK
2	LEDA
3	NC
4	VCI
5	IOVCC
6	NC
7	IM1
8	IM3
9	GND
10	GND
11	VS
12	HS
13	PCLK
14	DE
15	GND
16	D0
17	D1
18	D2
19	D3
20	D4
21	D5
22	D6
23	D7
24	D8
25	D9
26	D10
27	D11
28	D12
29	D13
30	D14
31	D15
32	D16
33	D17
34	D18
35	D19
36	D20
37	D21
38	D22
39	D23
40	RESET
41	RD
42	CS
43	DCX
44	WR/SCL
45	SDI
46	SDO
47	NC
48	NC
49	NC
50	NC

SYM.	DESCRIPTION OF REVISION	REASON	REVISED BY	DATE
A	first issue	XG, SU	XG, SU	2019/10/14
B	modify backlight		XG, SU	2023/09/20

AMSON

于都上晴電子有限公司
YU DU AMSON ELECTRONICS Co.,Ltd.

TITLE: OUTLINE DIMENSION

DRAWN BY:
CHECKED BY:
APPROVED BY:

D/N:AM240320-024L
Rev:B
SCALE: 1:1
SHEET NO. 1 OF 1
UNIT: mm

4. Interface Description

PIN NO.	PIN NAME	DESCRIPTION
1	LEDK	The cathode of LED power
2	LEDA	The Anode of LED power
3	NC	NC
4	VCI	Analog operating voltage.
5	IOVCC	Logic operating voltage.
6~9	IM0~IM3	MPU interface mode select pin,(FYI NOTE1)
10	GND	Power ground
11	VSYNC	Frame synchronizing signal for RGB interface operation.
12	HSYNC	Line synchronizing signal for RGB interface operation.
13	DOTCLK	Dot clock signal for RGB interface operation.
14	DE	Data enable signal for RGB interface operation.
15	GND	Power ground
16-33	DB0-DB17	Data bus
34`39	DB18~DB23	NC
40	RESET	Reset pin setting either pin low initializes the LSI Must be reset after power supplied
41	RD	Read signal input terminal, Active at 'L'.
42	CS	Chip select signal input terminal, Active at 'L'
43	/WR	Write enable in MCU parallel interface Display data/command selection pin in 4-line serial interface. - Second Data lane in 2 data lane serial interface. -If not used, please fix this pin at VDDI or DGND.
44	DCX /SCL	Display data/command selection pin in parallel interface. This pin is used to be serial interface clock DCX='1': display data or parameter DCX='0': command data.
45	SDI	When IM [3]: Low, Serial in/out signal. When IM [3]: High, Serial input signal. The data is applied on the rising edge of the SCL signal.
46	SDO	Serial output signal. The data is applied on the rising edge of the SCL signal.

47	NC	NC
48	NC	NC
49	NC	NC
50	NC	NC

Note1:

-The MCU interface mode select.

IM3	IM2	IM1	IM0	MPU Interface Mode	Data pin
0	0	0	0	80-8bit parallel I/F	DB[7:0]
0	0	0	1	80-16bit parallel I/F	DB[15:0]
0	0	1	0	80-9bit parallel I/F	DB[8:0]
0	0	1	1	80-18bit parallel I/F	DB[17:0],
0	1	0	1	3-line 9bit serial I/F	SDA: in/out
0	1	0	1	2 data lane serial I/F	SDA: in/out WRX: in
0	1	1	0	4-line 8bit serial I/F	SDA: in/out
1	0	0	0	80-16bit parallel I/F Ⅱ	DB[17:10], DB[8:1]
1	0	0	1	80-8bit parallel I/F Ⅱ	DB[17:10]
1	0	1	0	80-18bit parallel I/F Ⅱ	DB[17:0],
1	0	1	1	80-9bit parallel I/F Ⅱ	DB[17:9]
1	1	0	1	3-line 9bit serial I/F Ⅱ	SDA: in/ SDO: out
1	1	1	0	4-line 8bit serial I/F Ⅱ	SDA:in/ SDO: out

If not used, please fix this pin at VDDI or DGND.

5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	V
Analog Supply Voltage	VCI	-0.3	4.6	V
Input Voltage	Vin	-0.3	IOVCC +0.3	V
Operating Temperature	T_{OP}	-20	70	°C
Storage Temperature	T_{ST}	-30	80	°C
Storage Humidity	HD	20	90	%RH

6. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	2.8	3.3	V	-
Analog Supply Voltage	VCI	2.5	2.8	3.3	V	-
Input High Voltage	V_{IH}	0.7VCI	-	VCI	V	-
Input Low Voltage	V_{IL}	GND	-	0.3 VCI	V	-
Output High Voltage	V_{OH}	0.8 VCI	-	VCI	V	-
Output Low Voltage	V_{OL}	GND	-	0.2 VCI	V	-
I/O Leak Current	I_{LI}	-1	-	1	uA	-
Supply Current	IDD	-	7.0	10	mA	-

7. Timing Characteristics
7.1 i80-System Interface Timing Characteristics
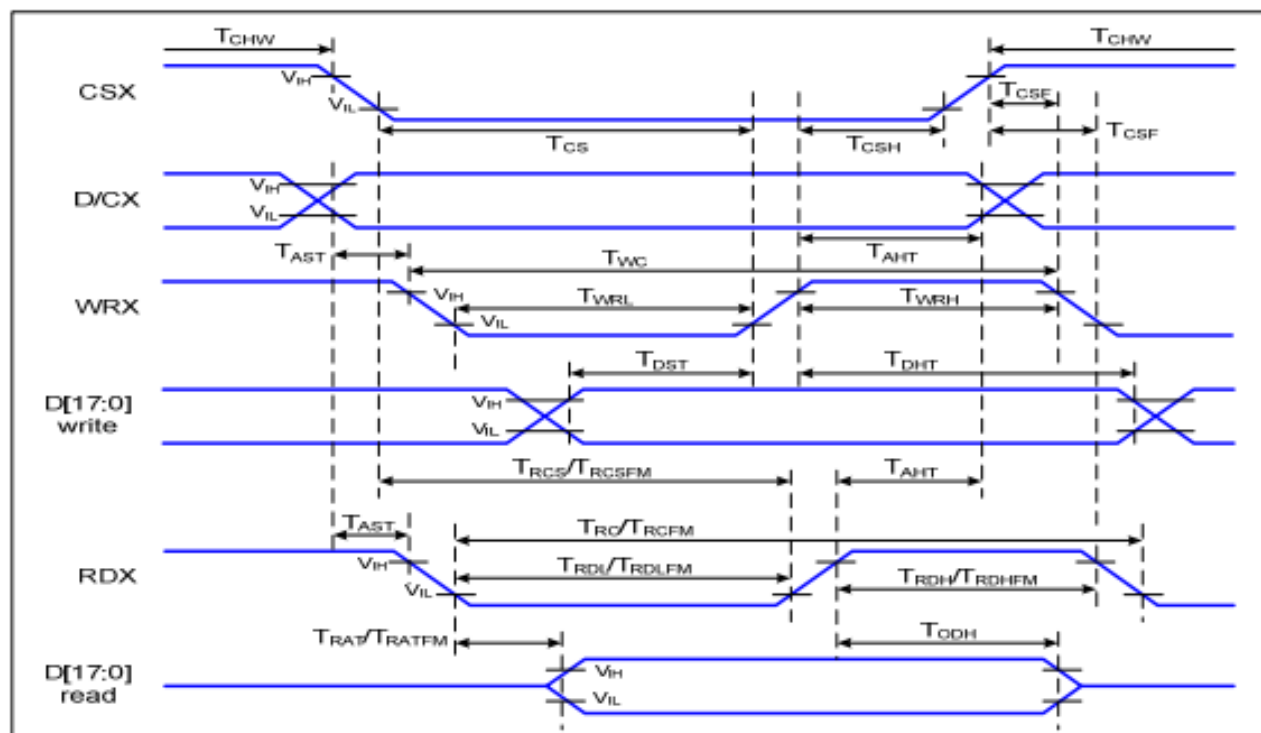
Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T_{AST}	Address setup time	0		ns	-
	T_{AHT}	Address hold time (Write/Read)	10		ns	
CSX	T_{CHW}	Chip select "H" pulse width	0		ns	-
	T_{CS}	Chip select setup time (Write)	15		ns	
	T_{RCS}	Chip select setup time (Read ID)	45		ns	
	T_{RCSFM}	Chip select setup time (Read FM)	355		ns	
	T_{CSF}	Chip select wait time (Write/Read)	10		ns	
	T_{CSH}	Chip select hold time	10		ns	
WRX	T_{WC}	Write cycle	66		ns	
	T_{WRH}	Control pulse "H" duration	15		ns	
	T_{WRL}	Control pulse "L" duration	15		ns	
RDX (ID)	T_{RC}	Read cycle (ID)	160		ns	When read ID data
	T_{RDH}	Control pulse "H" duration (ID)	90		ns	
	T_{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX (FM)	T_{RCFM}	Read cycle (FM)	450		ns	When read from frame memory
	T_{RDHFM}	Control pulse "H" duration (FM)	90		ns	
	T_{RDLFM}	Control pulse "L" duration (FM)	355		ns	
D[17:0]	T_{DST}	Data setup time	10		ns	For CL=30pF

|					
T_{DHT}	Data hold time	10		ns	
T_{RAT}	Read access time (ID)		40	ns	
T_{RATFM}	Read access time (FM)		340	ns	
T_{ODH}	Output disable time	20	80	ns	

7.2 Serial Interface Characteristics (3-line serial):

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 ℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

7.3 Serial Interface Characteristics (4-line serial):

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 ℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	-write command & data ram
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data ram
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
D/CX	T_{DCS}	D/CX setup time	10		ns	
	T_{DCH}	D/CX hold time	10		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

7.4 RGB Interface Characteristics:
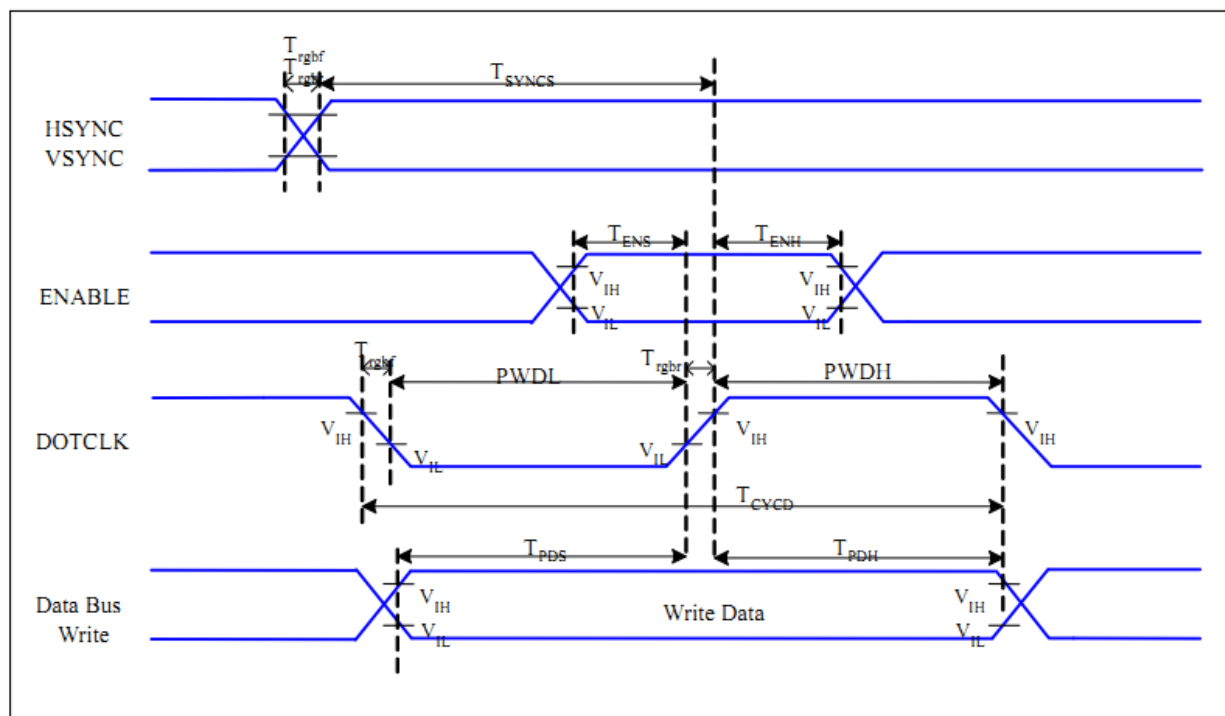
VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 ℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T$_{SYNCS}$	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	T$_{ENS}$	Enable Setup Time	25	-	ns	
	T$_{ENH}$	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	T$_{CYCD}$	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T$_{PDS}$	PD Data Setup Time	50	-	ns	
	T$_{PDH}$	PD Data Hold Time	50	-	ns	

Table 7 18/16 Bits RGB Interface Timing Characteristics

7.5 Reset Timing Characteristics
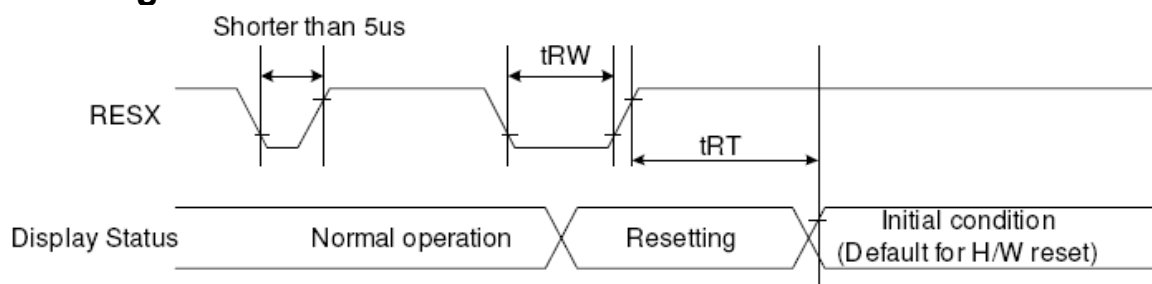
Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
				120 (note 1,6,7)	mS

Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:
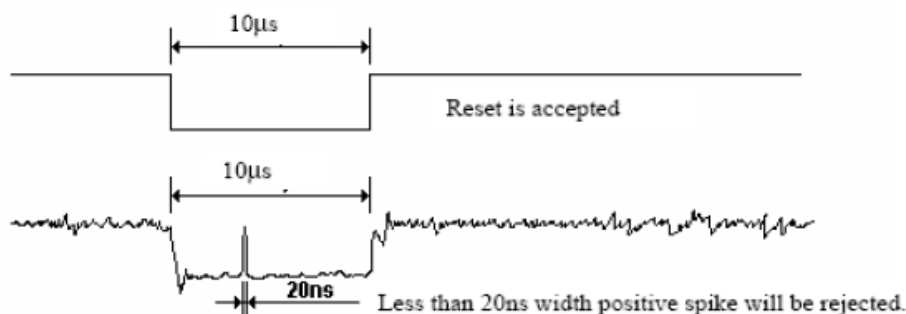
Note 5: When Reset applied during Sleep In Mode.

Note 6: When Reset applied during Sleep Out Mode.

Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

8. Backlight Characteristic
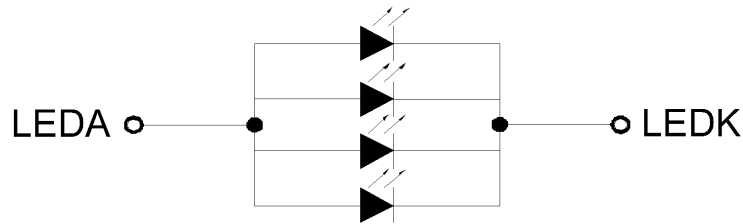
BL CIRCUIT DIAGRAM:

Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	2.9	3.2	3.5	V	If=80mA
Supply Current	If	-	80		mA	-
Luminous Intensity for LCM	-	350	400	-	cd/m^2	If=80mA
Uniformity for LCM	-	75	80	-	％	If=80mA
Life Time	-	-	50000	-	Hr	If=80mA
Backlight Color	White					

9. Optical Characteristics

Item	Conditions		Min.	Typ.	Max.	Unit	Note
Viewing Angle (CR>10)	Horizontal	θL	-	80	-	degree	(1),(2),(6)
		θR	-	80	-		
	Vertical	θT	-	80	-		
		θB	-	80	-		
Contrast Ratio	Center		600	800	-	-	(1),(3),(6)
Response Time	Rising + Falling		-	16	21	ms	(1),(4),(6)
CF Color Chromaticity (CIE1931)	Red x		Typ. -0.05	TBD	Typ. +0.05	-	(1), (6)
	Red y			TBD		-	
	Green x			TBD		-	
	Green y			TBD		-	
	Blue x			TBD		-	
	Blue y			TBD		-	
	White x			TBD		-	
	White y			TBD		-	
NTSC	CIE1931		-	55.3	-	%	(1),(6)

Note (1) Measurement Setup: The LCD module should be stabilized at given temp. 25°C for 15 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 15 minutes in a windless room.
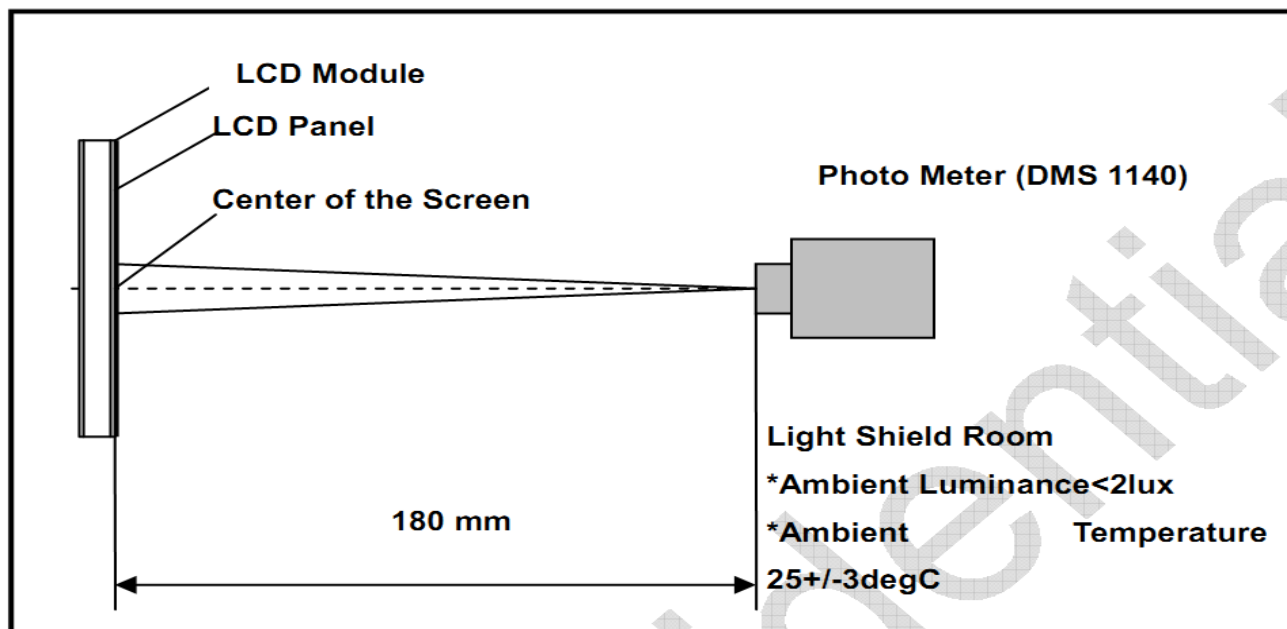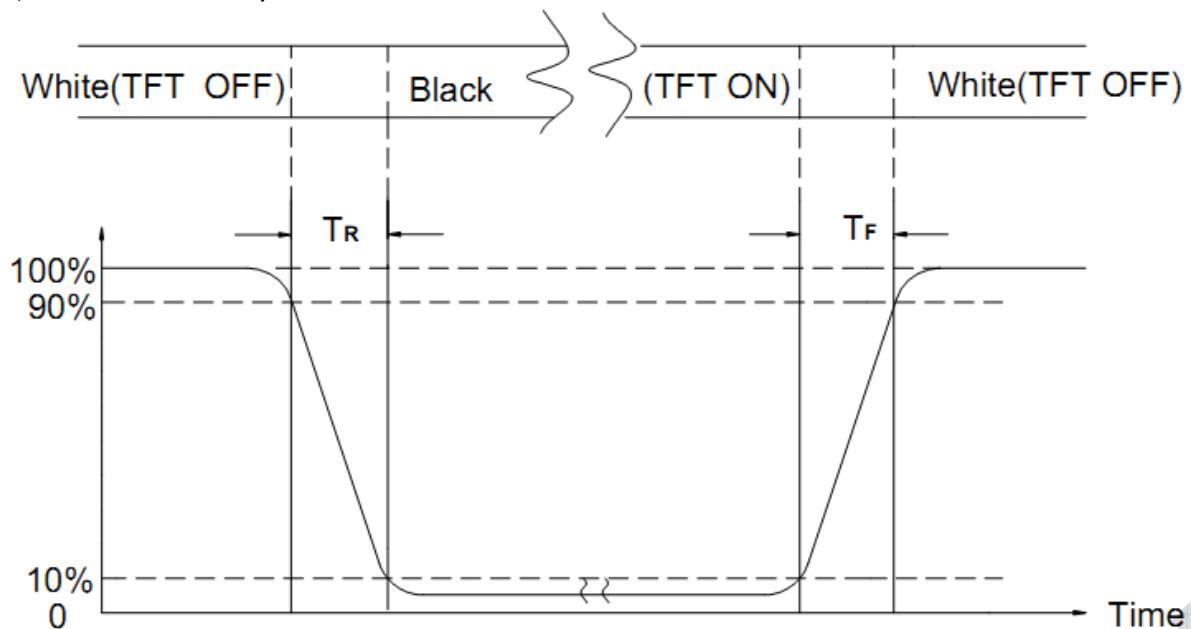
Note (2) Definition of Viewing Angle
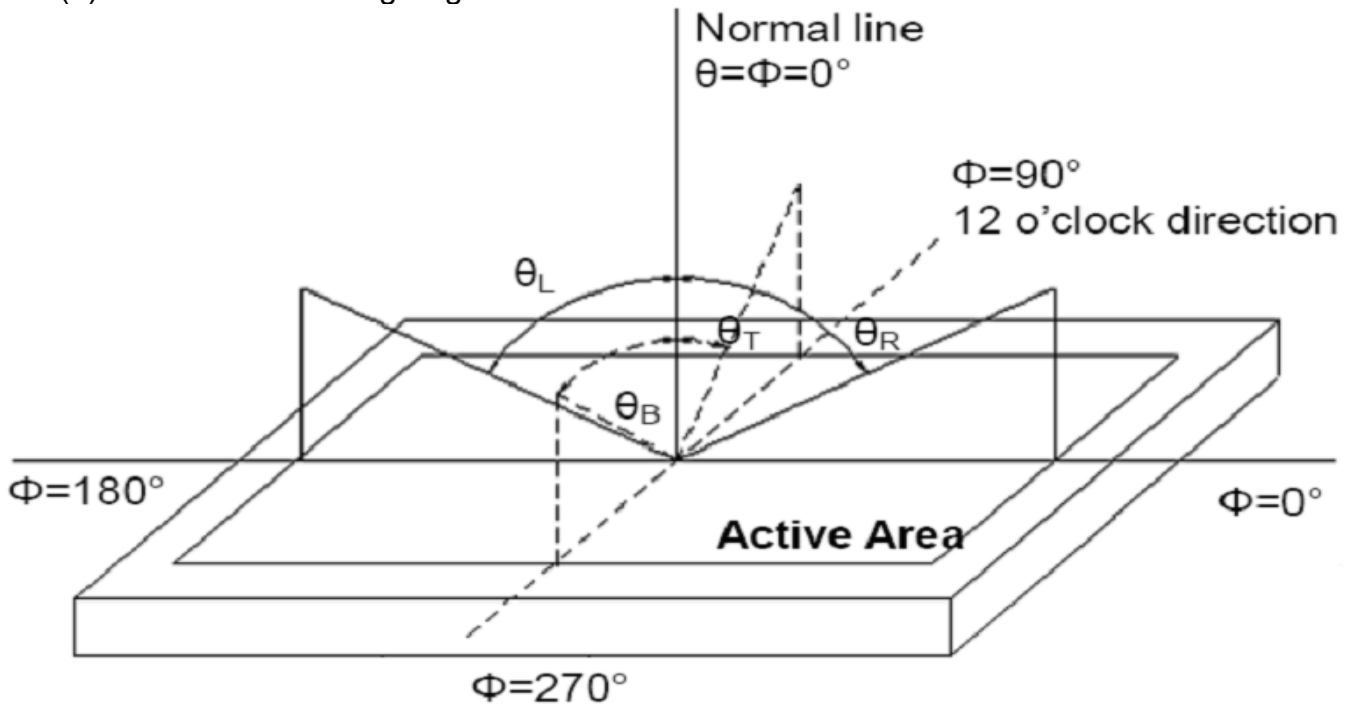
Note (3) Definition of Contrast Ratio (CR)

   The contrast ratio can be calculated by the following expression

   Contrast Ratio (CR) = L63 / L0

   L63: Luminance of gray level 63, L0: Luminance of gray level 0

Note (4) Definition of response time

Note (5) Definition of Transmittance (Module is without signal input)

   Transmittance = Center Luminance of LCD / Center Luminance of Back Light x 100%

Note (6) Definition of color chromaticity (CIE1931)

      Color coordinates measured at the center point of LCD

10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
	High Temperature Storage	80°C±2°C×96Hours	Inspection after 2~4hours storage at room temperature, the samples should be free from defects: 1, Air bubble in the LCD. 2, Seal leak. 3, Non-display. 4, Missing segments. 5, Glass crack. 6, Current IDD is twice higher than initial value. 7, The surface shall be free from damage. 8, The electric characteristic requirements shall be satisfied.
	Low Temperature Storage	-30°C±2°C×96Hours	
	High Temperature Operating	70°C±2°C×96Hours	
	Low Temperature Operating	-20°C±2°C×96Hours	
	Temperature Cycle(Storage)	-20°C ⟷ 25°C ⟷ 70°C (30min) (5min) (30min) 1cycle Total 10cycle	
	Damp Proof Test (Storage)	50°C±5°C×90%RH×120Hours	
	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5MM X,Y,Z direction for total 3hours (packing condition test will be tested by a carton)	
	Drooping Test	Drop to the ground from 1M height one time every side of carton. (packing condition test will be tested by a carton)	
	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:

1, The Test samples should be applied to only one test item.

2, Sample side for each test item is 5~10pcs.

3,For Damp Proof Test, Pure water(Resistance＞10MΩ)should be used.

4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.

5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.

6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

11. Inspection Standard

11.1. QUALITY :

THE QUALITY OF GOODS SUPPLIED TO PURCHASER SHALL COME UP TO THE FOLLOWING STANDARD.

11.1.1. THE METHOD OF PRESERVING GOODS

AFTER DELIVERY OF GOODS FROM AMSON TO PURCHASER. PURCHASER SHALL CONTROL THE LCM AT -10℃ TO 40℃ ,AND IT MIGHT BE DESIRABLE TO KEEP AT THE NORMAL ROOM TEMPERATURE AND HUMIDITY UNTIL INCOMING INSPECTION OR THROWING INTO PROCESS LINE.

11.1.2. INCOMING INSPECTION

(A) THE METHOD OF INSPECTION

IF PURCHASER MAKE AN INCOMING INSPECTION , A SAMPLING PLAN SHALL BE APPLIED ON THE CONDITION THAT QUALITY OF ONE DELIVERY SHALL BE REGARDED AS ONE LOT.

(B) THE STANDARD OF QUALITY

ISO-2859-1 (SAME AS MIL-STD-105E) , LEVEL Ⅱ SINGLE PLAN.

CLASS	AQL(%)
CRITICAL	0.4 %
MAJOR	0.65 %
MINOR	1.5 %
TOTAL	1.5 %

EVERY ITEM SHALL BE INSPECTED ACCORDING TO THE CLASS.

(C) MEASURE

IF AS THE RESULT OF ABOVE RECEIVING INSPECTION , A LOT OUT IS DISCOVERED. PURCHASER SHALL BE INFORM SELLER OF IT WITHIN SEVEN DAYS. BUT FIRST SHIPMENT WITHIN FOURTEEN DAYS.

11.1.3. WARRANTY POLICY

AMSON WILL PROVIDE ONE-YEAR WARRANTY FOR THE PRODUCTS ONLY IF UNDER SPECIFICATION OPERATING CONDITIONS. AMSON WILL REPLACE NEW PRODUCTS FOR THESE DEFECT PRODUCTS WHICH UNDER WARRANTY PERIOD AND BELONG TO THE RESPONSIBILITY OF AMSON.
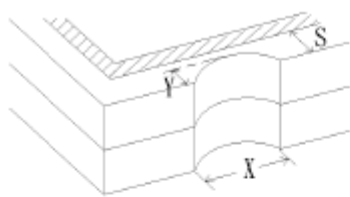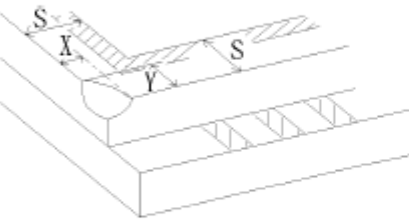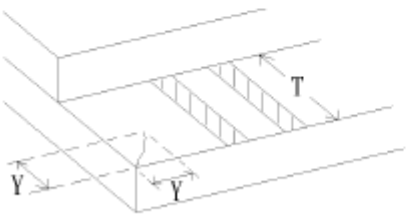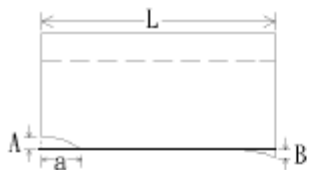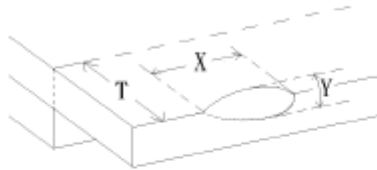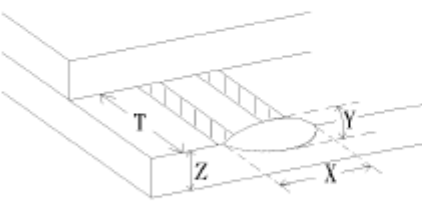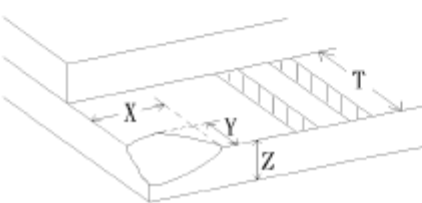
11.2. CHECKING CONDITION

11.2.1. CHECKING DIRECTION SHALL BE IN THE 45 DEGREE AREA TO FACE THE SAMPLE.

11.2.2. CHECKER SHALL SEE OVER 300±25 mm. WITH BARE EYES FAR FROM SAMPLE AND USING 2 PCS. OF 20W FLUORESCENT LAMP.

11.3. INSPECTION PLAN :

CLASS	ITEM	JUDGEMENT	CLASS
PACKING & INDICATE	1. OUTSIDE AND INSIDE PACKAGE	"MODEL NO." , "LOT NO." AND "QUANTITY" SHOULD INDICATE ON THE PACKAGE.	Minor
	2. MODEL MIXED AND QUANTITY	OTHER MODEL MIXED...............REJECTED QUANTITY SHORT OR OVER......REJECTED	Critical
	3. PRODUCT INDICATION	"MODEL NO." SHOULD INDICATE ON THE PRODUCT	Major
ASSEMBLY	4. DIMENSION, LCD GLASS SCRATCH AND SCRIBE DEFECT.	ACCORDING TO SPECIFICATION OR DRAWING.	Major
APPEARANCE	5. VIEWING AREA	POLARIZER EDGE OR LCD'S SEALING LINE IS VISABLE IN THE VIEWING AREA ....REJECTED	Minor
	6. BLEMISH、BLACK SPOT、WHITE SPOT IN THE LCD AND LCD GLASS CRACKS	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	7. BLEMISH、BLACK SPOT WHITE SPOT AND SCRATCH ON THE POLARIZER	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	8. BUBBLE IN POLARIZER	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	9. LCD'S RAINBOW COLOR	STRONG DEVIATION COLOR (OR NEWTON RING) OF LCD......REJECTED. OR ACCORDING TO LIMITED SAMPLE (IF NEEDED, AND INSIDE VIEWING AREA)	Minor
ELECTRICAL	10. ELECTRICAL AND OPTICAL CHARACTERISTICS (CONTRAST、VOP、CHROMATICITY ... ETC)	ACCORDING TO SPECIFICATION OR DRAWING . (INSIDE VIEWING AREA)	Critical
	11.MISSING LINE	MISSING DOT、LINE、CHARACTER ....REJECTED	Critical
	12.SHORT CIRCUIT、WRONG PATTERN DISPLAY	NO DISPLAY、WRONG PATTERN DISPLAY、CURRENT CONSUMPTION OUT OF SPECIFICATION...... REJECTED	Critical
	13. DOT DEFECT (FOR COLOR AND TFT)	ACCORDING TO STANDARD OF VISUAL INSPECTION	Minor

11.4. STANDARD OF VISUAL INSPECTION

NO.	CLASS	ITEM	JUDGEMENT
11.4.1	MINOR	BLACK AND WHITE SPOT FOREIGN MATERIEL DUST IN THE CELL BLEMISH SCRATCH	(A) ROUND TYPE: see table below
11.4.2	MINOR	BUBBLE IN POLARIZER DENT ON POLARIZER	see table below
11.4.3	MINOR	Dot Defect	see below

11.4.1 (A) ROUND TYPE: unit : mm.

DIAMETER (mm.)	ACCEPTABLE Q'TY
$\Phi \leqq 0.2$	3 (Distance>5mm)
$0.2 < \Phi \leqq 0.25$	1 (Distance>5mm)
$0.25 < \Phi$	0

NOTE: $\Phi=(LENGTH+WIDTH)/2$

(B) LINEAR TYPE: unit : mm.

LENGTH	WIDTH	ACCEPTABLE Q'TY
------	$W \leqq 0.03$	Distance>1mm
$L \leqq 4.0$	$0.03 < W \leqq 0.05$	3 (Distance>15mm)
------	$0.05 < W$	FOLLOW ROUND TYPE

11.4.2 unit : mm.

DIAMETER	ACCEPTABLE Q'TY
$\Phi \leqq 0.2$	Distance>1mm
$0.2 < \Phi \leqq 0.5$	3 (Distance>15mm)
$0.5 < \Phi$	0

11.4.3

Items	ACC. Q'TY
Bright dot	$N \leqq 1$
Dark dot	$N \leqq 1$

Pixel Define :

Note 1: The definition of dot: The size of a defective dot over 1/2 of whole dot is regarded as one defective dot.

Note 2: Bright dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.

Note 3: Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green ,blue pattern.

NO.	CLASS	ITEM	JUDGEMENT	
11.4.4	MINOR	LCD GLASS CHIPPING		Y > S Reject
11.4.5	MINOR	LCD GLASS CHIPPING		X or Y > S Reject
11.4.6	MAJOR	LCD GLASS GLASS CRACK		Y > (1/2) T Reject
11.4.7	MAJOR	LCD GLASS SCRIBE DEFECT		1. a> L/3 , A>1.5mm. Reject 2. B : ACCORDING TO DIMENSION
11.4.8	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL AREA)		$\Phi = (x+y)/2 > 2.5$ mm Reject
11.4.9	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL SURFACE)		Y > (1/3) T Reject
11.4.10	MINOR	LCD GLASS CHIPPING		Y > T Reject

12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to POWER or GROUND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.

12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
  [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT , and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

TBD